CALCE Web Seminar:
Electronic Part Lifetime Buy Planning and Optimization

Date and Time:
May 29th start at 11:00am U.S. Eastern (8:00am U. S. Pacific)

Telecon and Webex:
Call-in number and URL to be announced

Abstract: Mismatches between electronic part procurement lifecycles and the lifecycles of the products that they are used in cause products with long manufacturing and/or support lives to incur significant obsolescence management costs. Lifetime buy is one of the most prevalent mitigation approaches employed for electronic part obsolescence management. Making lifetime purchases of parts when they go obsolete involves managing many interacting influences and multiple concurrent buys for multiple parts. There are multiple factors that contribute to the lifecycle cost associated with a lifetime buy: procurement cost, inventory cost, disposal cost, and penalty cost. The focus of this seminar is to summarize recent work at CALCE on optimizing lifetime buy quantities by minimizing lifecycle cost, and for predicting the confidence level obtained for particular buy sizes.

About the speaker: Professor Peter Sandborn has strong connections to the DMSMS community having been funded work on obsolescence management by the USAF Wright Labs Electronic Part Obsolescence Initiative, Lockheed Martin (Navy TREN T program), Northrop Grumman, NSWC, the National Science Foundation, and others. The CALCE obsolescence forecasting algorithms appear in several commercial tools, and the MOCA design refresh planning tool is used by organizations in the defense, avionics and telecommunications communities.

Prof. Sandborn is an Associate Professor in the CALCE Electronic Products and Systems Center (EPSC) at the University of Maryland. His interests include technology tradeoff analysis for electronic packaging, virtual qualification of electronic systems, parts selection and management for electronic systems, and system life cycle and risk economics. Prior to joining the University of Maryland, he was a founder and Chief Technical Officer of Savantage, Inc. Prof. Sandborn has a Ph.D. degree in electrical engineering from the University of Michigan and is the author of over 100 technical publications and several books on multichip module design and electronic parts. He is an Associate Editor for the IEEE Transactions on Electronics Packaging Manufacturing and a member of the editorial board of the International Journal of Performability Engineering.